

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended): A lithography system comprising:

an exposure apparatus which projects a pattern on to a substrate on which resist is coated,
a substrate processing apparatus provided adjacent to said exposure apparatus which processes

the substrate:

a first chamber containing the exposure apparatus therein;

a second chamber provided adjacent to the first chamber separately from said first chamber and
which contains the substrate processing apparatus therein;

an environment sensor provided in at least one of the first and the second chambers which measures
an environment of at least a portion in said at least one of the first and the second chambers; and

a control device electrically connected to the environment sensor, said control device controlling
the environment in said at least the other of the first and the second chambers on the basis of a measured
value given from said environment sensor in such a manner that the environment of at least a portion on a
side of said exposure apparatus becomes the same as the environment of at least a portion on a side of said
substrate processing apparatus.

2. (Previously Amended): A lithography system according to claim 1, wherein said environment sensor measures at least one of pressure, temperature and humidity in said at least one of the first and the second chambers.

3. (Original): A lithography system according to claim 2, wherein said substrate processing apparatus has at least one of a resist coating function and a developing function.

4. (Previously Amended): A lithography system according to claim 1, wherein the resist coated on the substrate is chemically amplified resist.

5. (Currently Amended): A lithography method for controlling an environment in an exposure apparatus which exposes a substrate and which is provided adjacent to a substrate processing apparatus which processes the substrate before or after exposure, the method comprising the steps of:

obtaining data regarding the environment of at least a portion in a processing chamber in which said substrate processing apparatus is provided; and

controlling the environment in an exposure chamber in which said exposure apparatus is provided and which is provided separately from the processing chamber, on the basis of the obtained data in such

a manner that the environment of at least a portion in said exposure chamber becomes the same as the environment in said processing chamber.

6. (Original): A method according to claim 5, wherein said substrate processing apparatus includes at least one of a coater which coats sensitive agent on the substrate before the exposure and a developer which develops the substrate after the exposure.

7. (Canceled)

8. (Original): A method according to claim 5, wherein the data relates to at least one of air pressure, temperature and humidity.

9. (Canceled)

10. (Original): A method according to claim 5, wherein said exposure apparatus and said substrate processing apparatus are assembled as an in-line system.

11. (Original): A method according to claim 5, wherein chemically amplified resist is coated on the substrate.

12. (Currently Amended): A lithography method for controlling an environment in a substrate processing apparatus which processes a substrate before or after exposure, said substrate processing apparatus being ~~connected to~~ provided adjacent to an exposure apparatus which exposes the substrate before or after the processing, the method comprising the steps of:

obtaining data regarding the environment of at least a portion in an exposure chamber in which said exposure apparatus is provided; and

controlling the environment in a processing chamber in which said processing apparatus is provided and which is provided separately from the exposure chamber, on the basis of the obtained data in such a manner that the environment of at least a portion in said substrate processing chamber becomes the same as the environment in said exposure chamber.

13. (Previously Amended): A method according to claim 12, wherein the processing apparatus includes at least one of a coater which coats sensitive agent on the substrate before the exposure and a developer which develops the substrate after the exposure.

14. (Canceled)

15. (Previously Amended): A method according to claim 12, wherein the data relates to at least one of air pressure, temperature and humidity.

16. (Canceled)

17. (Original): A method according to claim 12, wherein the data relates to at least one of air pressure, temperature and humidity.

18. (Canceled)

19. (Original): A method according to claim 12, wherein said exposure apparatus and said processing apparatus are assembled as an in-line system.

20. (Currently Amended): A method for making an exposure apparatus which exposes a substrate, said exposure apparatus being provided adjacent to a substrate processing apparatus contained in a

processing chamber which processes the substrate before or after exposure of the substrate, the method comprising the steps of:

providing an exposure body in an exposure chamber different from the processing chamber, the exposure body performing an exposure operation of the substrate;

providing an adjusting device which adjusts an environment of at least a portion in said exposure chamber; and

providing a control device which controls said adjusting device on the basis of data regarding the environment in said processing chamber in such a manner that the environment in said exposure chamber becomes the same as the environment of at least a portion in said processing chamber.

21. (Original): A method according to claim 20, wherein said substrate processing apparatus includes at least one of a coater which coats sensitive agent on the substrate before the exposure and a developer which develops the substrate after the exposure.

22. (Original): A method according to claim 20, wherein the data relates to at least one of air pressure, temperature and humidity.

23. (Currently Amended) A method for making a substrate processing apparatus which processes a substrate and which is provided adjacent to an exposure apparatus contained in an exposure chamber which exposes the substrate before or after the processing of the substrate, the method comprising the steps of:

providing an exposure body in a processing chamber different from the exposure chamber, the processing body performing a processing operation to the substrate;

providing an adjusting device which adjusts an environment of at least a portion in said processing chamber; and

providing a control device which controls said adjusting device on the basis of data regarding the environment in said exposure chamber in such a manner that the environment in said processing chamber becomes the same as the environment of at least a portion in said exposure chamber.

24. (Original): A method according to claim 23, wherein said substrate processing apparatus includes at least one of a coater which coats sensitive agent on the substrate before the exposure and a developer which develops the substrate after the exposure.

25. (Original): A method according to claim 23, wherein the data relates to at least one of air pressure, temperature and humidity.

26. (Currently Amended): A lithography method using an exposure apparatus which exposes a substrate and a substrate processing apparatus which processes the substrate before or after exposure, the method comprising the steps of:

obtaining data regarding an environment of at least a portion within a chamber of one of an exposure chamber in which said exposure apparatus is contained and a processing chamber in which said substrate processing apparatus is contained and which is provided separately from the exposure chamber; and

controlling the environment in the other chamber of the exposure chamber and the processing chamber on the basis of the obtained data in such a manner that the environment of at least a portion in one of said exposure chamber and said processing chamber becomes the same as the environment in the other of said chambers.

27. (Currently Amended): An exposure apparatus which exposes a substrate and which is provided adjacent to a substrate processing apparatus contained in a processing chamber which processes the substrate before or after exposure of the substrate, the exposure apparatus comprising:

an exposure chamber which is separate from the processing chamber and contains the exposure apparatus;

an adjusting device connected to said exposure chamber and which adjusts an environment of at least a portion in said exposure chamber; and

a control device electrically connected to said adjusting device and which controls said adjusting device on the basis of data regarding the environment of at least a portion in said processing chamber in such a manner that the environment in said exposure chamber becomes the same as the environment in said processing chamber.

28. (Currently Amended): A substrate processing apparatus which processes a substrate and which is provided adjacent to an exposure apparatus contained in an exposure chamber which exposes the substrate before or after the substrate processing, the substrate processing apparatus comprising:
a processing chamber which is separate from the exposure chamber and contains the substrate processing apparatus;

an adjusting device connected to said processing chamber and which adjusts an environment of at least a portion in said processing chamber; and

a control device electrically connected to said adjusting device and which controls said adjusting device on the basis of data regarding environment of at least a portion in said exposure chamber in such a manner that the environment in said processing chamber becomes the same as the environment in said exposure chamber.

29. (Previously Presented): A lithography system according to claim 3, wherein the resist coated on the substrate is chemically amplified resist.

30. (New): A lithography system according to claim 1, wherein the control device at least controls an environment near a portion where said first chamber and said second chamber are connected to each other.